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Application No.: 10/788,756

**FEB 08 2006**

**In the Claims**

Please amend Claims 1, 3, 7 and 9.

Please cancel Claims 2, 10-12, 14-15 without prejudice.

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LISTING OF CLAIMS

1. (currently amended) A particle-removing wafer, comprising:
  - a support body comprises a silicon wafer; and
  - a particle-adherent layer having a particle-adherent surface carried by said support body.
- 2 (canceled)
3. (currently amended) The particle-removing wafer of claim 1 wherein said particle-adherent layer comprises a plastic polytetrafluoroethylene film.
4. (original) The particle-removing wafer of claim 3 wherein said support body comprises a silicon wafer.
5. (original) The particle-removing wafer of claim 1 further comprising an adhesive layer provided between said support body and said particle-adherent layer.
6. (original) The particle-removing wafer of claim 5 wherein said support body comprises a silicon wafer.
7. (currently amended) The particle-removing wafer of claim 5 wherein said particle-adherent layer comprises a plastic polytetra-fluoroethylene film.
8. (original) The particle-removing wafer of claim 7 wherein said support body

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comprises a silicon wafer.

9. (currently amended) A particle-removing wafer, comprising:
  - a support body, said support body comprises a silicon wafer;
  - a resilient layer carried by said support body;
  - an adhesive layer carried by said resilient layer; and
  - a particle-adherent layer having a particle-adherent surface carried by said adhesive layer, said particle-adherent layer comprises a tetrafluoroethylene film.

10-12 (cancelled)

13. (original) The particle-removing wafer of claim 9 wherein said adhesive layer comprises a pair of adhesive surfaces.

14-16 (cancelled)

17. (withdrawn) A method of removing particles from a surface, comprising the steps of:
  - providing a particle-removing wafer having a particle-adherent surface;
  - placing said particle-adherent surface into contact with the particles on the surface; and
  - removing said particle-removing wafer from the surface.

18. (withdrawn) The method of claim 17 wherein said particle-removing wafer comprises a support body and a particle-adherent layer carried by said support body, and wherein said particle-adherent surface is provided on said particle-adherent layer.

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19. (withdrawn) The method of claim 18 wherein said support body comprises a silicon wafer.

20. (withdrawn) The method of claim 18 further comprising a resilient layer provided on said support body and an adhesive layer provided on said resilient layer, and wherein said particle-adherent layer is provided on said adhesive layer.